ON Semiconductor

Is Now



To learn more about onsemi™, please visit our website at www.onsemi.com

onsemi and ONSEMI. and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. onsemi reserves the right to make changes at any time to any products or information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/ or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use onsemi products for any such unintended or unauthorized application,



ON Semiconductor®

FDB8443-F085

N-Channel PowerTrench[®] MOSFET

40V, **80A**, **3.0m** Ω

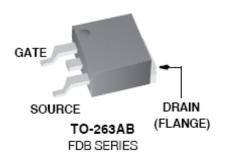
Features

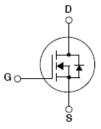
- Typ $r_{DS(on)}$ = 2.3m Ω at V_{GS} = 10V, I_D = 80A
- Typ $Q_{g(10)}$ = 142nC at V_{GS} = 10V
- Low Miller Charge
- Low Q_{rr} Body Diode
- UIS Capability (Single Pulse and Repetitive Pulse)
- Qualified to AEC Q101
- RoHS Compliant

Applications

- Automotive Engine Control
- Powertrain Management
- Solenoid and Motor Drivers
- Electronic Steering
- Integrated Starter / Alternator
- Distributed Power Architecture and VRMs
- Primary Switch for 12V Systems







Units

Max

MOSFET Maximum Ratings $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter		Ratings	Units
V_{DSS}	Drain to Source Voltage		40	V
V_{GS}	Gate to Source Voltage		±20	V
	Drain Current Continuous (T _C < 146°C, V _{GS} = 10V)		80	
I_D	Continuous ($T_{amb} = 25^{\circ}C$, $V_{GS} = 10V$, with $R_{\theta JA} = 43^{\circ}C/W$)		25	Α
	Pulsed		See Figure 4	
E _{AS}	Single Pulse Avalanche Energy	(Note 1)	531	mJ
П	Power Dissipation		188	W
P_{D}	Derate above 25°C		1.25	W/°C
T _J , T _{STG}	Operating and Storage Temperature		-55 to +175	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance Junction to Case	0.8	°C/W
$R_{\theta JA}$	Thermal Resistance Junction to Ambient (Note 2)	62	°C/W
$R_{\theta JA}$	Thermal Resistance Junction to Ambient TO-263, 1in ² copper pad area	43	°C/W

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDB8443	FDB8443-F085	TO-263AB	330mm	24mm	800 units

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted

Parameter

Gate to Source Leakage Current

Off Characteristics							
B _{VDSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0$	V	40	-	-	V
1	Zero Gate Voltage Drain Current	V _{DS} = 32V,		-	-	1	^
IDSS	Zero Gate voltage Drain Current	$V_{GS} = 0V$	$T_{\rm C} = 150^{\rm o}{\rm C}$	-	-	250	μΑ

 $V_{GS} = \pm 20V$

Test Conditions

Min

Тур

On Characteristics

Symbol

 I_{GSS}

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 250 \mu A$	2	2.8	4	V
		$I_D = 80A, V_{GS} = 10V$	-	2.3	3.0	
r _{DS(on)}	Drain to Source On Resistance	$I_D = 80A, V_{GS} = 10V,$ $T_J = 175^{\circ}C$	-	4.2	5.5	mΩ

Dynamic Characteristics

C _{iss}	Input Capacitance	V _{DS} = 25V, V _{GS} = 0V, f = 1MHz		-	9310	-	pF
C _{oss}	Output Capacitance			-	800	-	pF
C _{rss}	Reverse Transfer Capacitance	1 - 11/11/12	T = TIVIHZ		510	-	pF
R_G	Gate Resistance	$V_{GS} = 0.5V, f = 1MI$	Hz	-	0.9	-	Ω
$Q_{g(TOT)}$	Total Gate Charge at 10V	V _{GS} = 0 to 10V		-	142	185	nC
$Q_{g(TH)}$	Threshold Gate Charge	$V_{GS} = 0$ to 2V	V _{DD} = 20V	-	17.5	23	nC
Q_{gs}	Gate to Source Gate Charge		$I_{D} = 35A$	-	36	-	nC
Q _{gs2}	Gate Charge Threshold to Plateau		$I_g = 1mA$	-	18.8	-	nC
Q_{gd}	Gate to Drain "Miller" Charge			-	32	-	nC

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units

Switching Characteristics ($V_{GS} = 10V$)

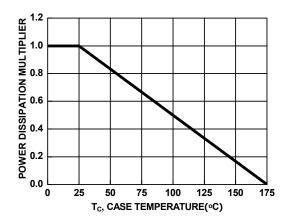
t _{on}	Turn-On Time		-	-	58	ns
$t_{d(on)}$	Turn-On Delay Time	.,	1	18.4	1	ns
t _r	Rise Time	V_{DD} = 20V, I_{D} = 35A V_{GS} = 10V, R_{GS} = 2 Ω	-	17.9	-	ns
t _{d(off)}	Turn-Off Delay Time	V _{GS} = 10V, R _{GS} = 2Ω	-	55	-	ns
t _f	Fall Time		-	13.5	-	ns
t _{off}	Turn-Off Time		-	-	109	ns

Drain-Source Diode Characteristics

V	Source to Drain Diode Voltage	I _{SD} = 35A	-	8.0	1.25	V
v_{SD}	Source to Drain blode voltage	I _{SD} = 15A	-	8.0	1.0	V
t _{rr}	Reverse Recovery Time	$I_{SD} = 35A$, $dI_{SD}/dt = 100A/\mu s$	-	42	55	ns
Q _{rr}	Reverse Recovery Charge		-	48	62	nC

1: Starting T_J = 25°C, L = 0.26mH, I_{AS} = 64A. 2: Pulse width = 100s.

Typical Characteristics



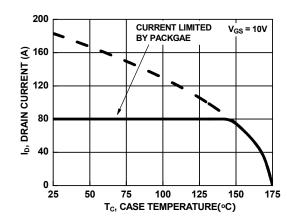


Figure 1. Normalized Power Dissipation vs Case Temperature

Figure 2. Maximum Continuous Drain Current vs Case Temperature

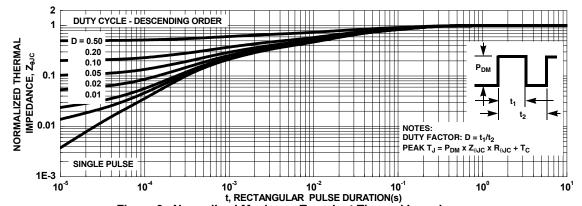


Figure 3. Normalized Maximum Transient Thermal Impedance

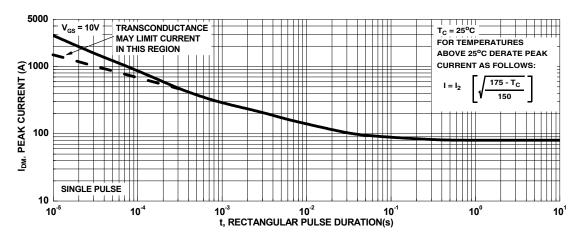


Figure 4. Peak Current Capability

Typical Characteristics

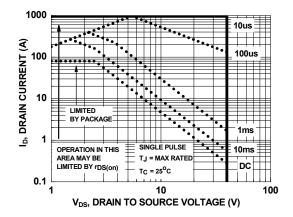


Figure 5. Forward Bias Safe Operating Area

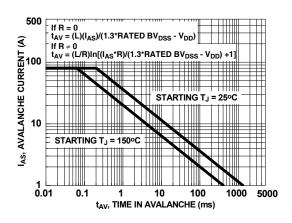


Figure 6. Unclamped Inductive Switching Capability

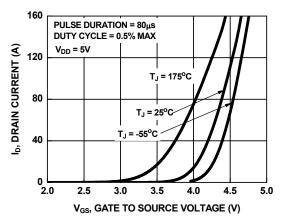


Figure 7. Transfer Characteristics

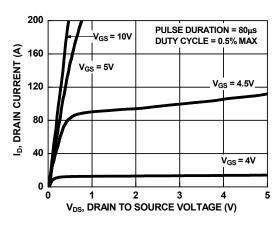


Figure 8. Saturation Characteristics

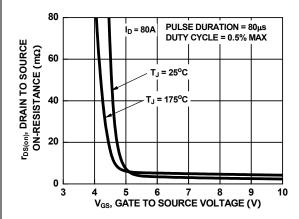


Figure 9. Drain to Source On-Resistance Variation vs Gate to Source Voltage

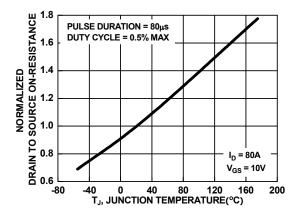


Figure 10. Normalized Drain to Source On Resistance vs Junction Temperature

Typical Characteristics

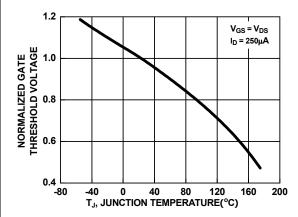


Figure 11. Normalized Gate Threshold Voltage vs Junction Temperature

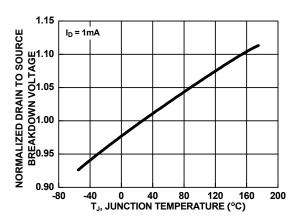


Figure 12. Normalized Drain to Source Breakdown Voltage vs Junction Temperature

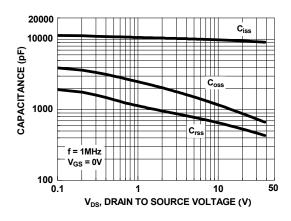


Figure 13. Capacitance vs Drain to Source Voltage

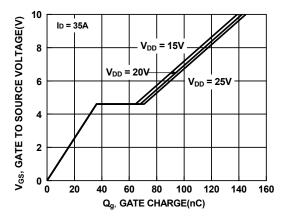


Figure 14. Gate Charge vs Gate to Source Voltage

ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hol

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800-282-9855 Toll Free USA/Canada Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910

Phone: 421 33 790 2910

Japan Customer Focus Center
Phone: 81–3–5817–1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative